Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **QB**
2. **QC**
3. **QD**
4. **QE**
5. **QF**
6. **QG**
7. **QH**
8. **GND**
9. **QH1**
10. **SRCLR**
11. **SRCK**
12. **RCK**
13. **G**
14. **SER**
15. **QA**
16. **VCC**

**.110”**

**14 13 12**

**11**

**10**

**9**

**8**

**7**

**15**

**16**

**1**

**2**

**3 4 5 6**

**.092”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: Vcc**

**Mask Ref: HC590E**

**APPROVED BY: DK DIE SIZE .092” X .110” DATE: 1/28/20**

**MFG: TEXAS INSTRUMENTS THICKNESS .015” P/N: 54HC595**

**DG 10.1.2**

#### Rev B, 7/19/02